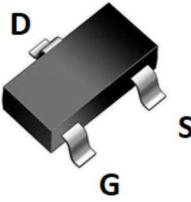
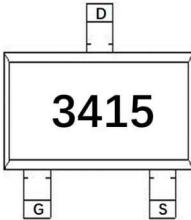
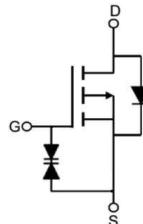


## Description

### PECJ P-channel Enhancement Mode Power MOSFET

<b>Features</b>	<b>Application</b>	
<ul style="list-style-type: none"> <li><math>V_{DS} = -20V, I_D = -4.5A</math></li> <li><math>R_{DS(ON)} &lt; 48m\Omega @ V_{GS} = -4.5V</math></li> <li><math>R_{DS(ON)} &lt; 65m\Omega @ V_{GS} = -2.5V</math></li> <li>Advanced Trench Technology</li> <li>Excellent <math>R_{DS(ON)}</math> and Low Gate Charge</li> <li>Lead free product is acquired</li> <li>ESD Rating: HBM 2.0KV</li> </ul>	<ul style="list-style-type: none"> <li>PWM Applications</li> <li>Load Switch</li> <li>Power Management</li> </ul>	
 SOT-23 top view	 Marking and pin Assignment	 Schematic Diagram

## Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
3415	PECJ3415KC	TAPING	SOT-23	7inch	3000	180000

## Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise specified)

Symbol	Parameter		Max.	Units
$V_{DSS}$	Drain-Source Voltage		-20	V
$V_{GSS}$	Gate-Source Voltage		$\pm 8$	V
$I_D$	Continuous Drain Current		-4.5	A
	$T_A = 100^\circ C$	-3		
$I_{DM}$	Pulsed Drain Current note1		-18	A
$P_D$	Power Dissipation	$T_A = 25^\circ C$	1.5	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		83.3	$^\circ C/W$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +150	$^\circ C$

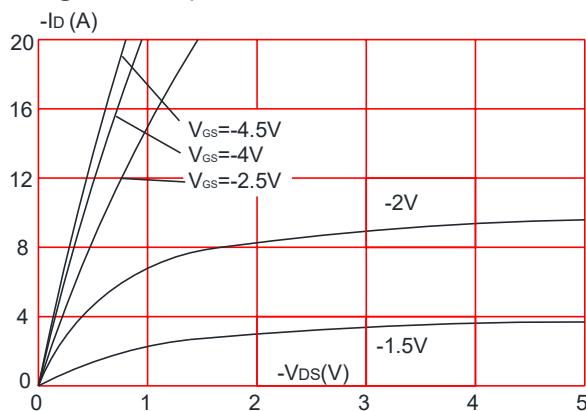
## Electrical Characteristics ( $T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=-250\mu\text{A}$	-20	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=-20\text{V}$ , $V_{GS}=0\text{V}$ ,	-	-	-1	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 8\text{V}$	-	-	$\pm 10$	$\text{uA}$
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=-250\mu\text{A}$	-0.35	-0.55	-0.9	V
$R_{DS(\text{on})}$ note2	Static Drain-Source on-Resistance	$V_{GS}=-4.5\text{V}$ , $I_D=-4\text{A}$	-	35	48	$\text{m}\Omega$
		$V_{GS}=-2.5\text{V}$ , $I_D=-3\text{A}$	-	42	65	
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=-10\text{V}$ , $V_{GS}=0\text{V}$ , $f=1.0\text{MHz}$	-	950	-	pF
$C_{oss}$	Output Capacitance		-	165	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	120	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=-10\text{V}$ , $I_D=-4.5\text{A}$ , $V_{GS}=-4.5\text{V}$	-	12	-	nC
$Q_{gs}$	Gate-Source Charge		-	1.4	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	3.6	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=-10\text{V}$ , $I_D=-2\text{A}$ , $R_G=3\Omega$ , $V_{GEN}=-4.5\text{V}$ , $R_L=2.5\Omega$	-	12	-	ns
$t_r$	Turn-on Rise Time		-	10	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	19	-	ns
$t_f$	Turn-off Fall Time		-	25	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current		-	-	-4.5	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-18	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_s=-4.5\text{A}$	-	-	-1.2	V

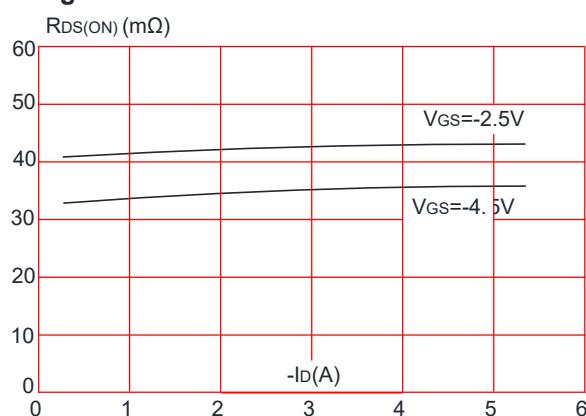
Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 2\%$

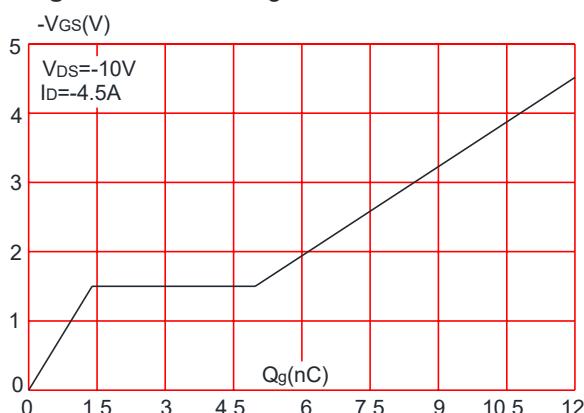
**Figure1:** Output Characteristics



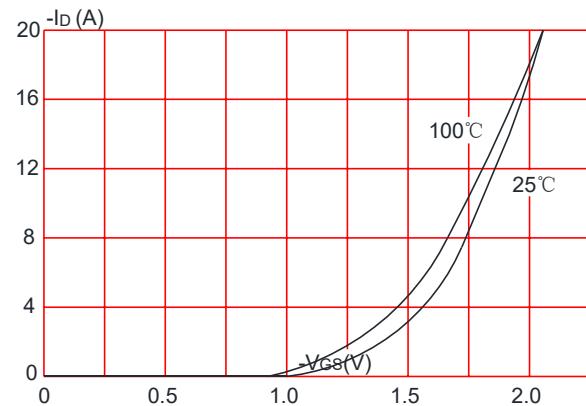
**Figure 3:** On-resistance vs. Drain Current



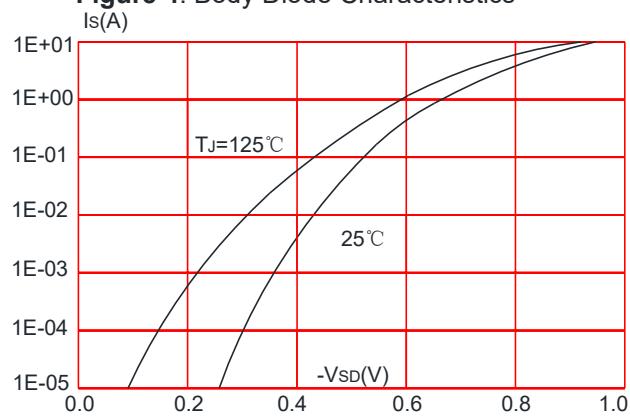
**Figure 5:** Gate Charge Characteristics



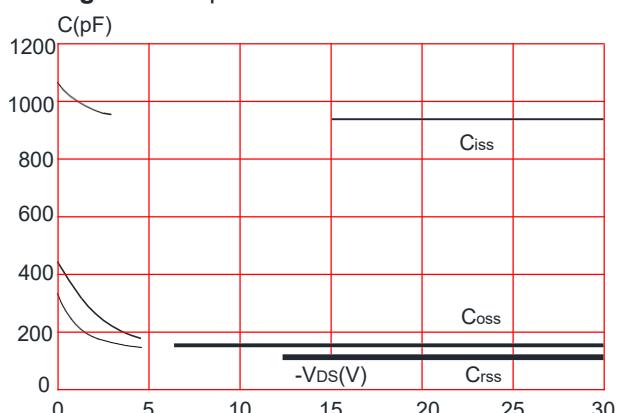
**Figure 2:** Typical Transfer Characteristics



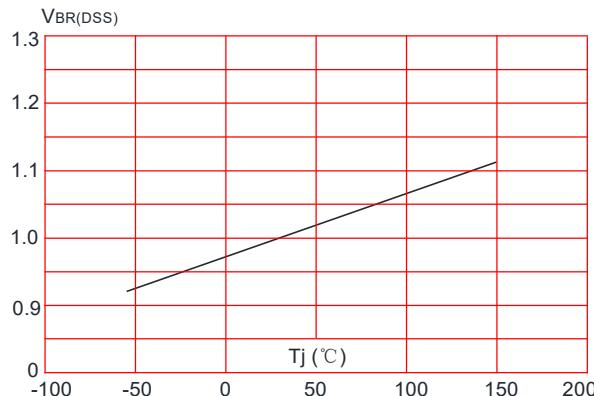
**Figure 4:** Body Diode Characteristics



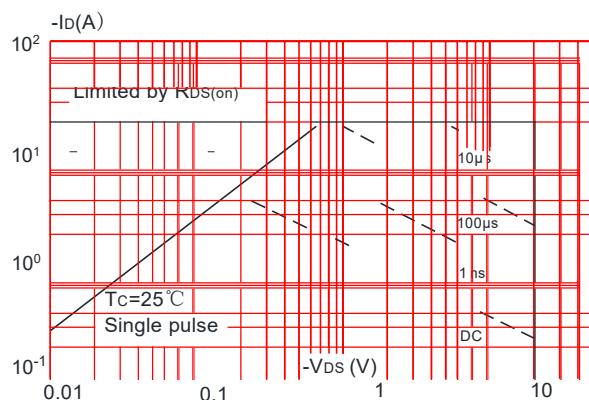
**Figure 6:** Capacitance Characteristics



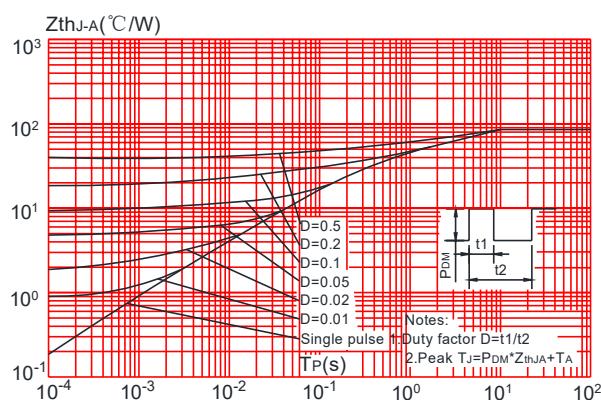
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



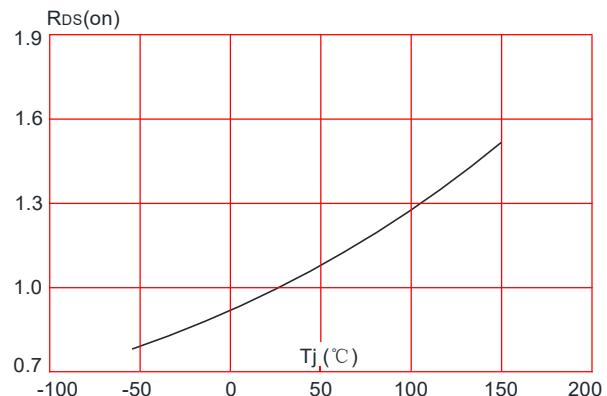
**Figure 9:** Maximum Safe Operating Area



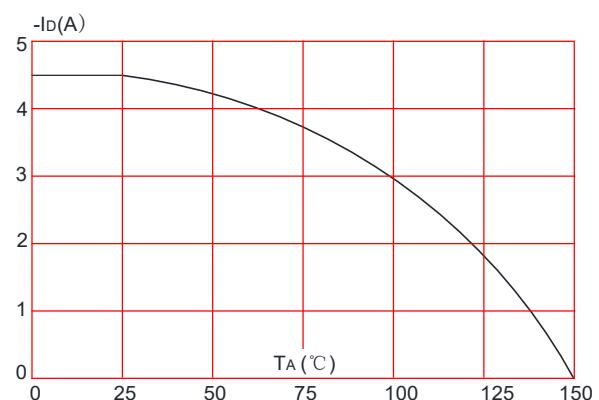
**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



**Figure 8:** Normalized on Resistance vs. Junction Temperature

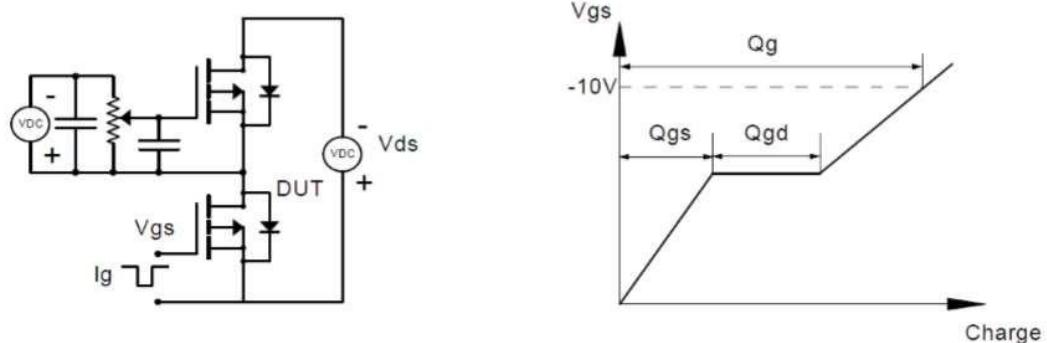


**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature

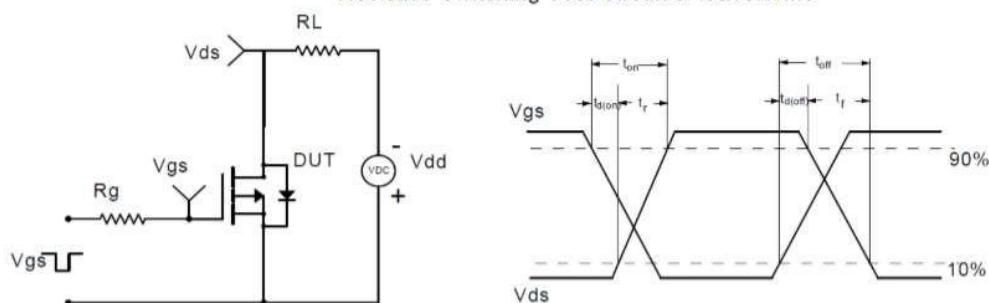


## Test Circuit

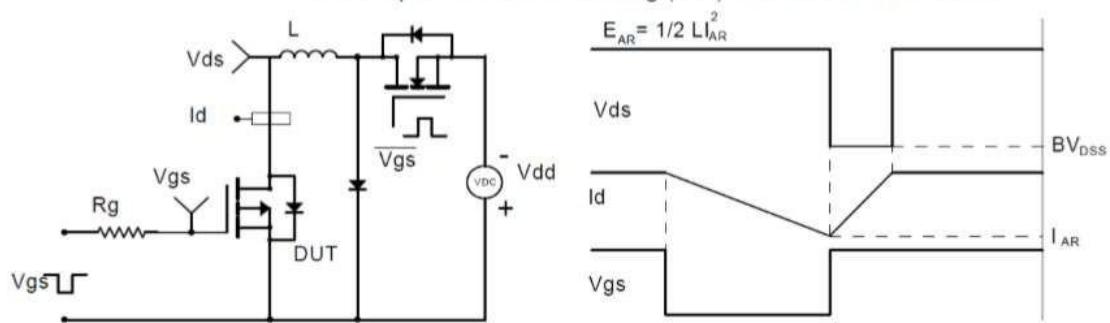
Gate Charge Test Circuit & Waveform



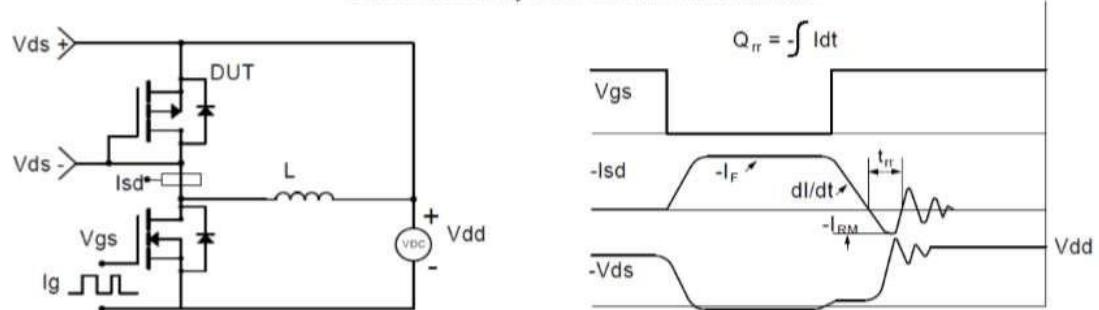
Resistive Switching Test Circuit & Waveforms



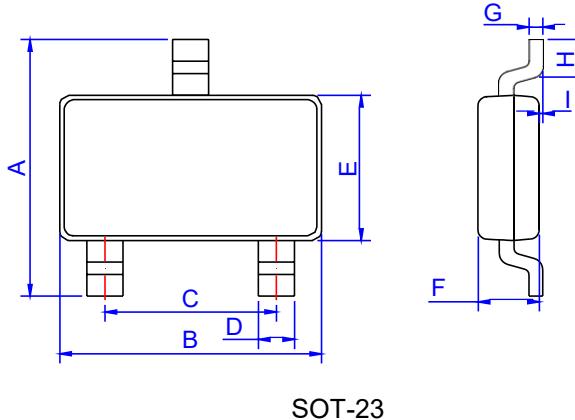
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

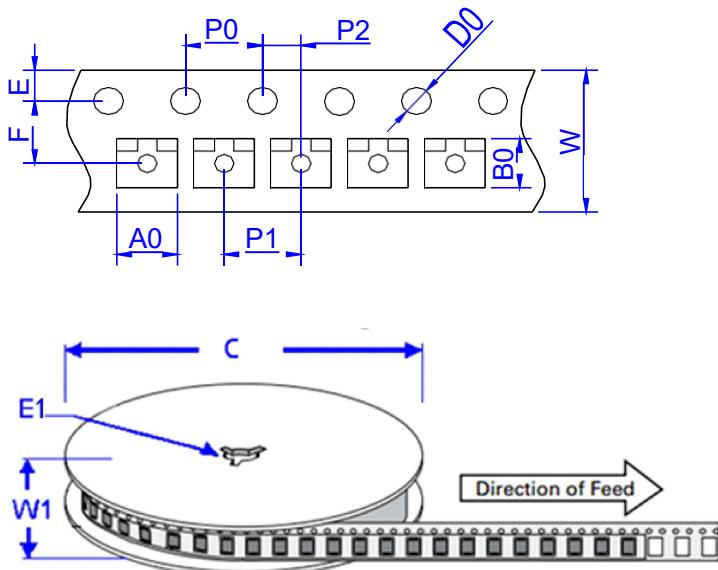


## Package Mechanical Data-SOT-23



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.30	2.40	2.50	0.091	0.095	0.098
B	2.80	2.90	3.00	0.110	0.114	0.118
C	1.90 REF			0.075 REF		
D	0.35	0.40	0.45	0.014	0.016	0.018
E	1.20	1.30	1.40	0.047	0.051	0.055
F	0.90	1.00	1.10	0.035	0.039	0.043
G		0.10	0.15		0.004	0.006
H	0.20			0.008		
I	0		0.10	0		0.004

## Package Information-SOT-23



Ref.	Dimensions	
	Millimeters	Inches
A0	3.15 ± 0.3	0.124 ± 0.012
B0	2.77 ± 0.3	0.109 ± 0.012
C	178	7.0
D0	1.50±0.1	0.059 ± 0.004
E	1.75 ± 0.2	0.069 ± 0.008
E1	13.3±0.3	0.524± 0.012
F	3.5 ± 0.2	0.138 ± 0.008
P0	4.00 ± 0.2	0.157 ± 0.008
P1	4.00 ± 0.2	0.157 ± 0.008
P2	2.00 ± 0.2	0.079 ± 0.008
W	8.00 ± 0.2	0.315 ± 0.008
W1	11.5±1.0	0.453 ± 0.039